

STARPOWER

SEMICONDUCTOR

IGBT

GD75FFL120C6S

Molding Type Module

1200V/75A 6 in one-package



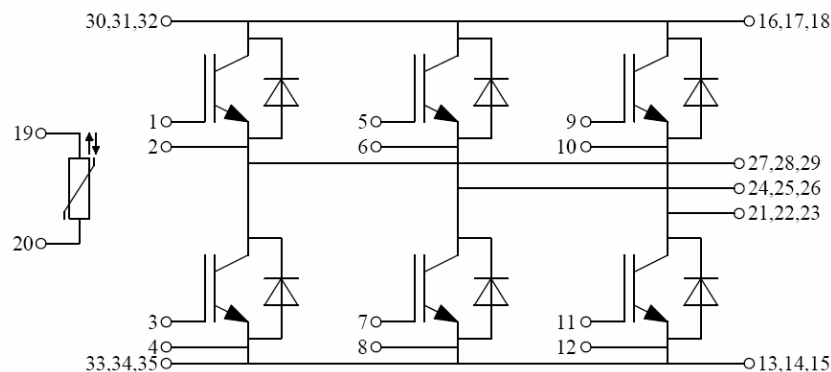
General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

Features

- High short circuit capability, self limiting to $6 \cdot I_C$
- $10\mu\text{s}$ short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Equivalent Circuit Schematic



Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders at f_{sw} up to 20kHz

Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Description	GD75FFL120C6S	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	120 75	A
$I_{CM(1)}$	Pulsed Collector Current	150	A
I_F	Diode Continuous Forward Current	75	A
I_{FM}	Diode Maximum Forward Current	150	A
P_D	Maximum power Dissipation @ $T_j=175^{\circ}\text{C}$	429	W
T_{SC}	Short Circuit Withstand Time @ $T_j=125^{\circ}\text{C}$	10	μs
T_j	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
I^2t -value, Diode	$V_R=0\text{V}$, $t=10\text{ms}$, $T_j=125^{\circ}\text{C}$	1190	A^2s
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
Mounting Torque	Mounting Screw:M5	3.0 to 6.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^{\circ}\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	$T_j=25^{\circ}\text{C}$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}$, $V_{GE}=0\text{V}$, $T_j=25^{\circ}\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$, $V_{CE}=0\text{V}$, $T_j=25^{\circ}\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=3.0\text{mA}$, $V_{CE}=V_{GE}$, $T_j=25^{\circ}\text{C}$	5.0	5.8	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=75\text{A}$, $V_{GE}=15\text{V}$, $T_j=25^{\circ}\text{C}$		1.9		V
		$I_C=75\text{A}$, $V_{GE}=15\text{V}$, $T_j=125^{\circ}\text{C}$		2.1		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=75A,$ $R_G=4.7\Omega, V_{GE} = \pm 15V,$ $T_j=25^\circ C$		260		ns
t_r	Rise Time			30		ns
$t_{d(off)}$	Turn-Off Delay Time			420		ns
t_f	Fall Time			70		ns
E_{on}	Turn-On Switching Loss			4.70		mJ
E_{off}	Turn-Off Switching Loss			6.20		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=75A,$ $R_G=4.7\Omega, V_{GE} = \pm 15V,$ $T_j=125^\circ C$		290		ns
t_r	Rise Time			50		ns
$t_{d(off)}$	Turn-Off Delay Time			520		ns
t_f	Fall Time			90		ns
E_{on}	Turn-On Switching Loss			6.75		mJ
E_{off}	Turn-Off Switching Loss			10.0		mJ
C_{ies}	Input Capacitance	$V_{CE} = 25V, f=1MHz,$ $V_{GE} = 0V$		5.30		nF
C_{oes}	Output Capacitance			0.38		nF
C_{res}	Reverse Transfer Capacitance			0.20		nF
I_{SC}	SC Data	$T_P \leq 10\mu s, V_{GE}=15V,$ $T_j=125^\circ C, V_{CC}=900V,$ $V_{CEM} \leq 1200V$		300		A
L_{CE}	Stray inductance			25		nH
$R_{CC'+EE'}$	Module lead resistance, terminal to chip	$T_C=25^\circ C$		1.80		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=75A$	$T_j=25^\circ C$	1.9	2.3	V
			$T_j=125^\circ C$	2.0	2.4	
t_{rr}	Diode Reverse Recovery Time	$I_F=75A,$ $V_R=600V,$ $di/dt=-2000A/\mu s,$ $V_{GE}=-15V$	$T_j=25^\circ C$	100		ns
			$T_j=125^\circ C$	125		
I_{RM}	Diode Peak Reverse Recovery Current		$T_j=25^\circ C$	80		A
			$T_j=125^\circ C$	100		
E_{rec}	Reverse Recovery Energy		$T_j=25^\circ C$	3.0		mJ
			$T_j=125^\circ C$	6.0		

Electrical Characteristics of NTC $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
R_{25}	Rated resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$R_{100}=439\Omega$	5		5	%
P_{25}	Power dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.35	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.58	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.009		K/W
Weight	Weight of Module	300		g

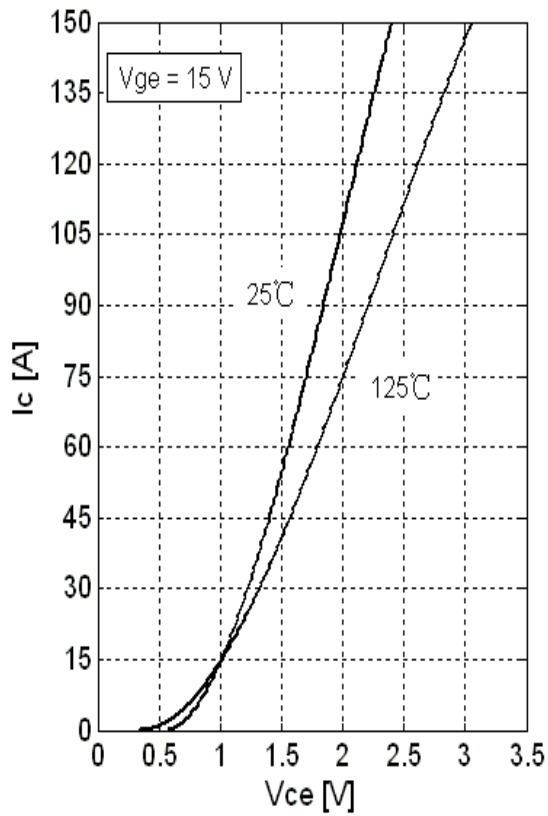


Fig 1. Typical Output Characteristics

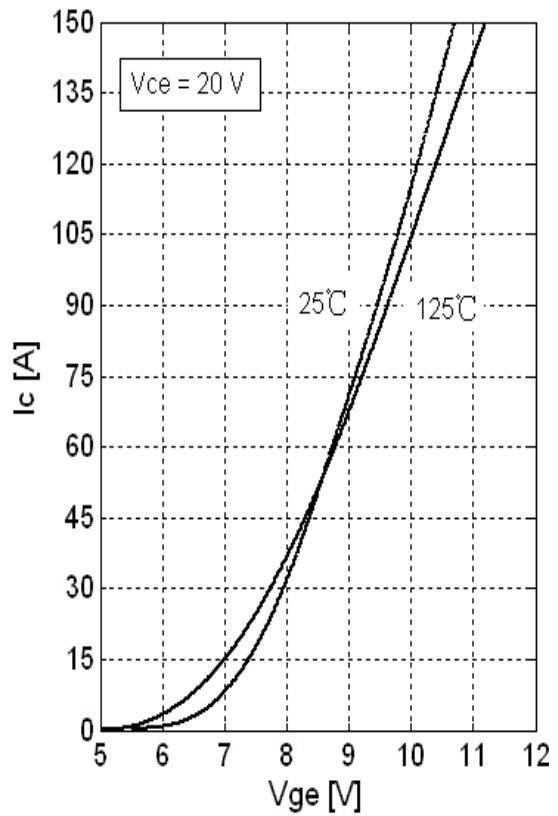


Fig 2. Typical Transfer Characteristics

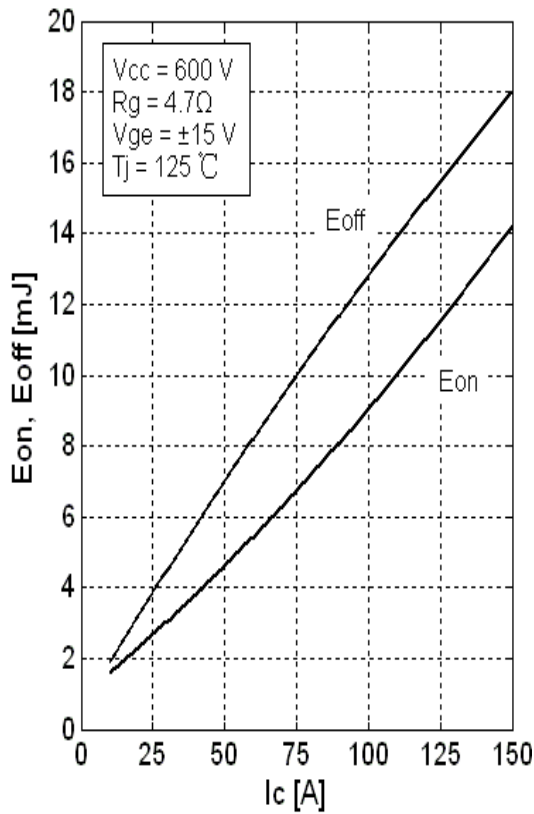


Fig 3. Switching Loss vs Collector Current

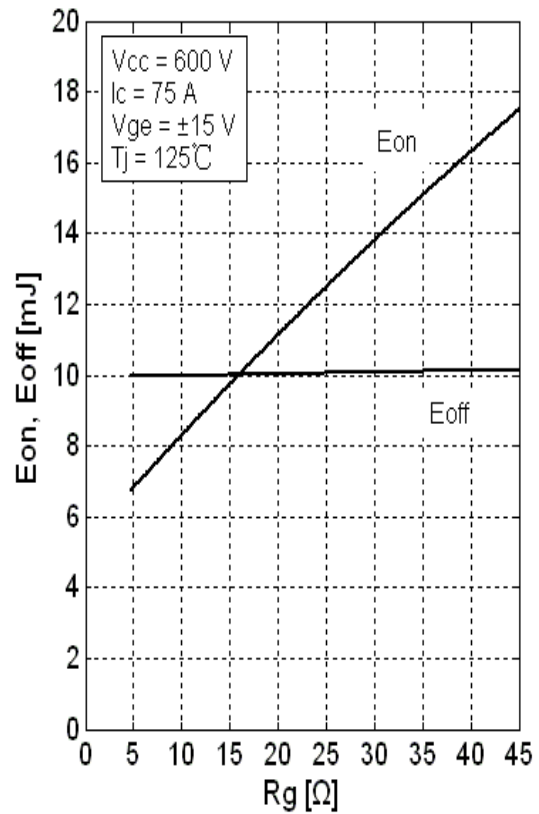


Fig 4. Switching Loss vs Gate Resistor

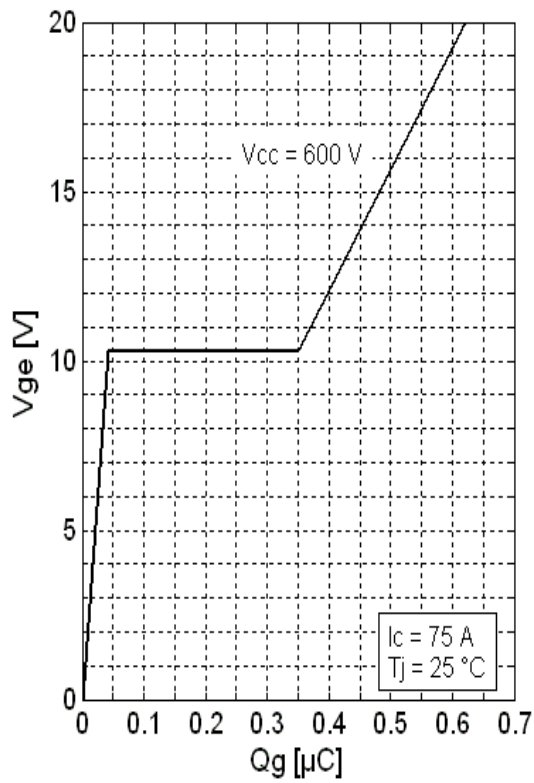


Fig 5. Gate Charge Characteristics.

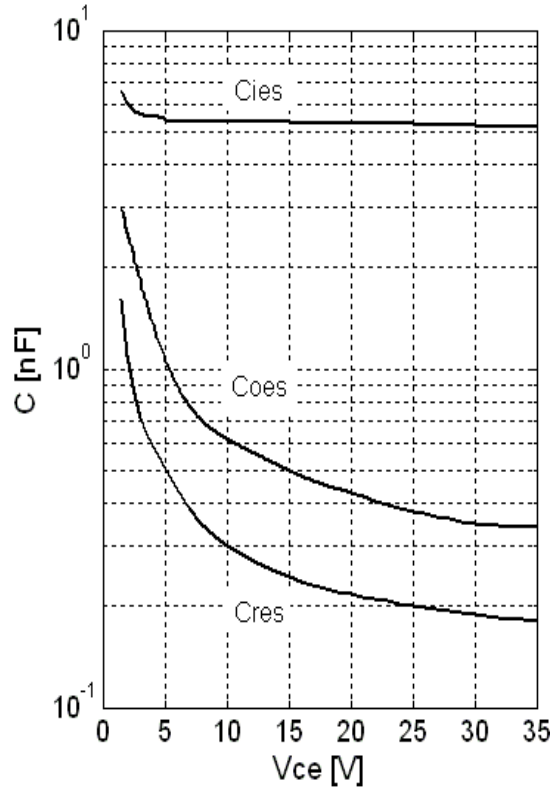


Fig 6. Typical Capacitance vs. Collector-Emitter Voltage

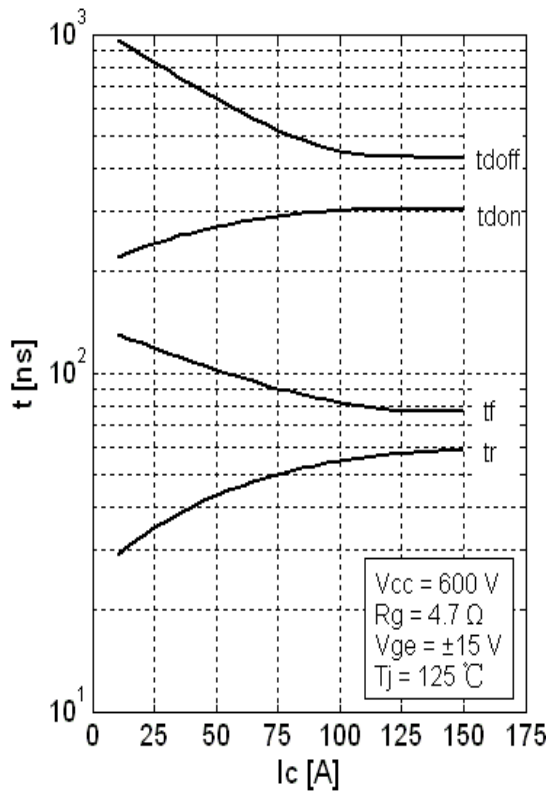


Fig 7. Typical Switching Times vs. I_C

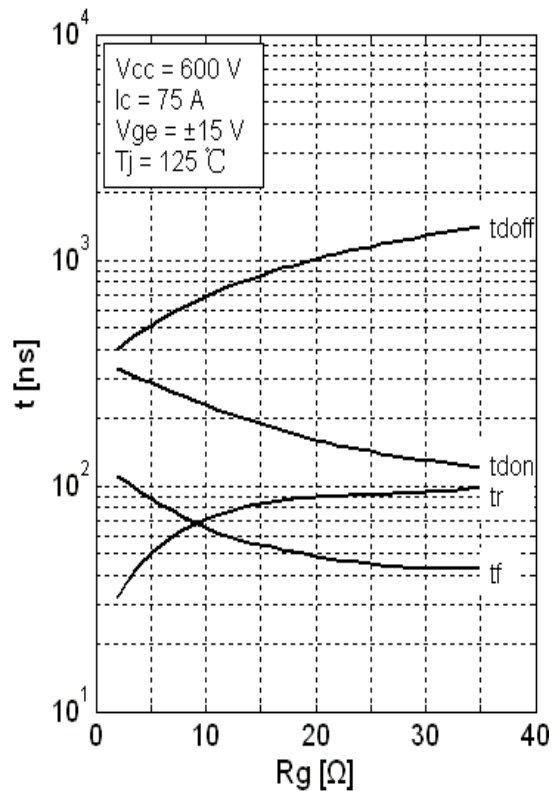


Fig 8. Typical Switching Times vs. Gate Resistance R_G

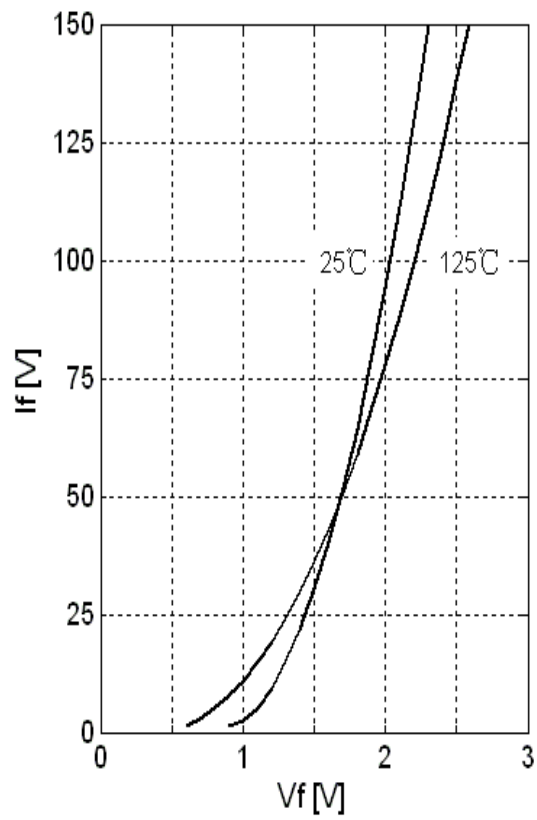


Fig 9. Typical Forward Characteristics (diode)

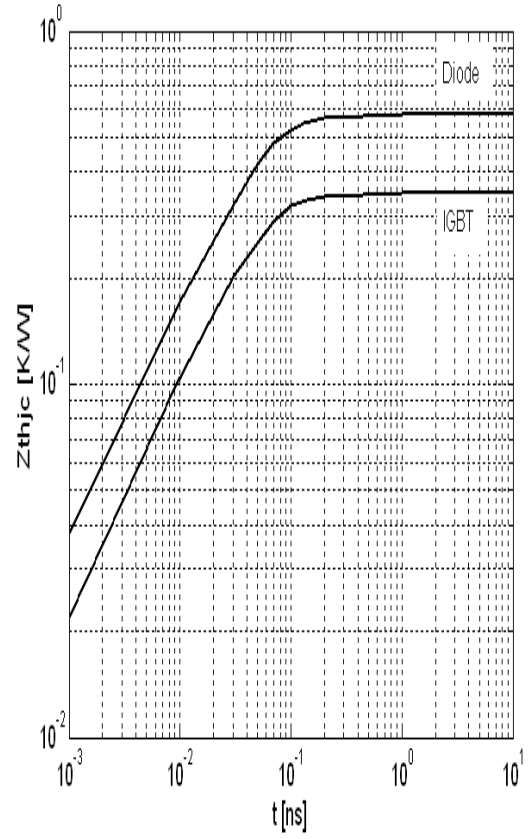


Fig 10. Transient thermal impedance

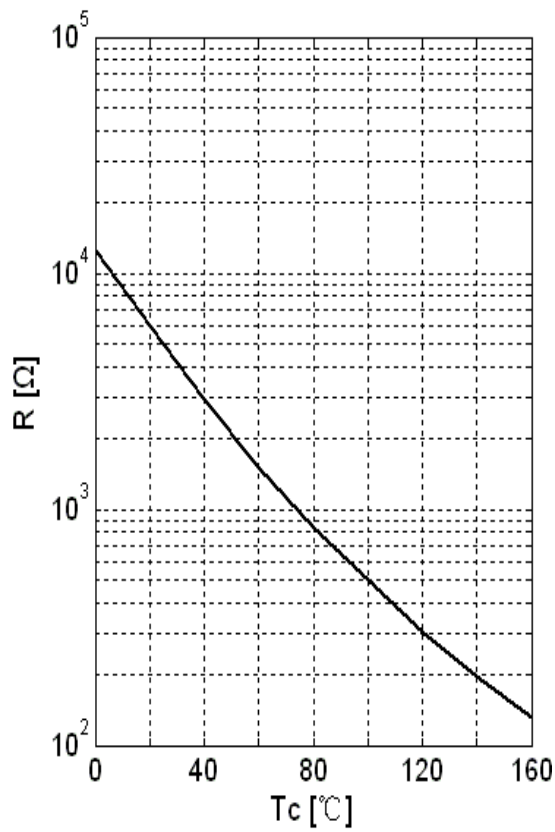
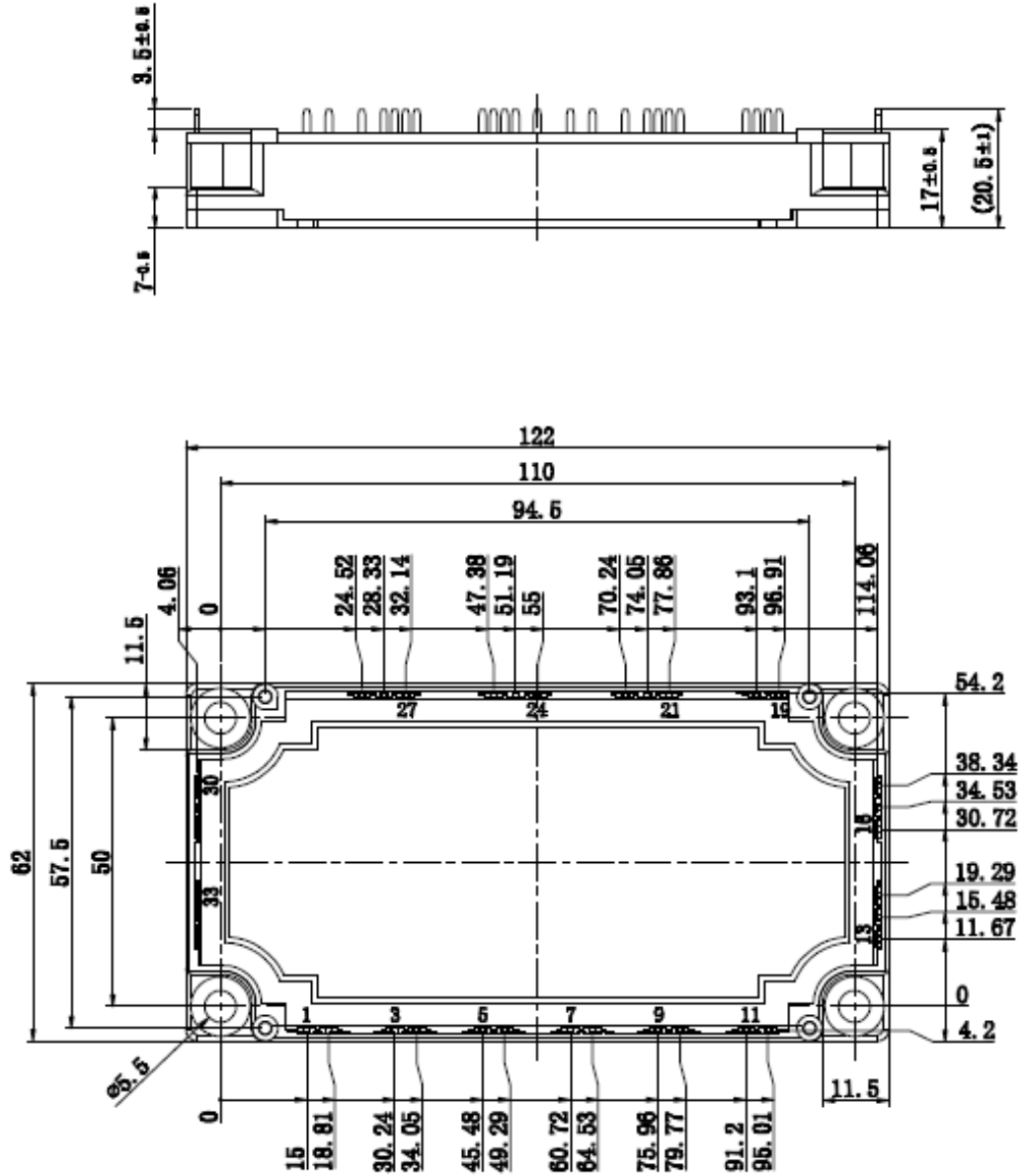


Fig 11. NTC-temperature characteristic

Package Dimension

Dimensions in Millimeters



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